







**HSEC8-DV SERIES** 

**MISALIGNMENT** 

**MITIGATION** 

(0.80 mm) .0315"

## **SPECIFICATIONS**

For complete specifications and recommended PCB layouts see www.samtec.com?HSEC8-DV

#### Insulator Material:

Black Liquid Crystal Polymer

# Contact:

Plating: Au or Sn over 50 μ" (1.27 μm) Ni Current Rating:

2.8 A per pin

2.6 A per pin (2 adjacent pins powered) Operating Temp: -55 °C to +125 °C RoHS Compliant:

### **PROCESSING**

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (10-60)

### RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality





#### **Card Mates:**

(1.60 mm) .062" card, (2.36 mm) .093" card, HSC8

#### **Cable Mates:**



or (2.36 mm) .093" cards

Mates with (1.60 mm) .062"

Custom designs compensate for misalignment. Contact Samtec.

#### HIGH-SPEED CHANNEL PERFORMANCE

VERTICAL EDGE RATE® CARD SOCKET

#### HSEC8-DV

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

# HSEC8

### **POSITIONS PER ROW**

No. of Positions x (0.80) .0315 + (7.80) .307

(No. of Positions + 6) x (0.80) .0315 + (0.60) .024

09, 13, 25, 37, 100

### **CARD THICKNESS**

### PLATING **OPTION**

(1.32) .052

# DV



**OTHER OPTION** 

## 09, 10, 13, 20, 25, 30, 37, 40, 49, 50, 60, 70, 80, 100

(13, 25, 49 only available with –L or –L2 option; 09 only available with –L2 option; 37 only available with -L option)

-01 (1.60 mm) .062" thick card -03 (2.36 mm) .093 thick card

= 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail

= 30 μ" (0.76 μm) Gold on contact, Matte Tin on tail

PER ROW	Α	В
09*†	(4.50) .177	(11.80) .465
13*†	(6.10) .240	(15.00) .591
25*†	(6.10) .240	(24.60) .969
37†	(18.10) .713	(34.20) 1.346
40	(18.90) .744	(36.60) 1.441
49*†	(22.90) .902	(43.80) 1.724
50	(22.90) .902	(44.60) 1.756
60	(26.90) 1.059	(52.60) 2.071
<b>70</b> †	(26.90) 1.059	(60.60) 2.386
80†	(26.90) 1.059	(68.60) 2.701
100†	(26.90) 1.059	(84.60) 3.331
Positions where no dimensions are given		

Mates with ECDP Series

#### → No. of Positions x (0.80) .0315 + (4.60) .181 (7.80).314 .307 **3333333333333333333333333333** .276 ₩**-**(1.12) .044 DIA (1.75) .070 ← (0.80) .0315 No. of Positions x (0.80) .0315 + (2.20) .087 10. 20 & 30

(7.01 mm) .276" DIA Polyimide Film Pick & Place Pad (with -01 card) (6.25 mm) .246" DIA Polyimide Film Pick & Place Pad (with -03 card)

### -BL

= Board Locks (40, 50, 60, 80 only) Other sizes availab Contact Samtec.) (Weld tab standard)

**Latching Option** (13, 25, 37, 49 only) (Weld tab standard)

### ·L2

= ECDP Latching (09, 13, 25, 49 only) (For use with ECDP) (Weld tab standard)

> -WT = Weld tab

# –TR

=Tape & Reel (09 - 70 only)

#### Notes:

While optimized for 50  $\Omega$ applications, this connector with alternative signal/ground patterns may also perform well in certain 75  $\Omega$  applications. Contact Samtec for further information.

CABLE | CONNECTOR ECDP-04 HSEC8-109-L2

ECDP-08 | HSEC8-113-L2

FCDP-16 HSFC8-125-L2

ECDP-32 HSEC8-149-L2

Some lengths, styles and options are non-standard, non-returnable.